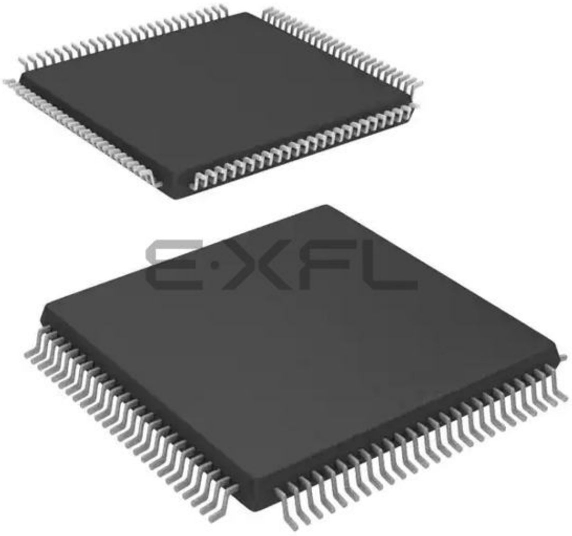
Intel - EPM7128BTC100-10 Datasheet



Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	10 ns
Voltage Supply - Internal	2.375V ~ 2.625V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	84
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128btc100-10

...and More Features

- System-level features
  - MultiVolt™ I/O interface enabling device core to run at 2.5 V, while I/O pins are compatible with 3.3-V, 2.5-V, and 1.8-V logic levels
  - Programmable power-saving mode for 50% or greater power reduction in each macrocell
  - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
  - Support for advanced I/O standards, including SSTL-2 and SSTL-3, and GTL+
  - Bus-hold option on I/O pins
  - PCI compatible
  - Bus-friendly architecture including programmable slew-rate control
  - Open-drain output option
  - Programmable security bit for protection of proprietary designs
  - Built-in boundary-scan test circuitry compliant with IEEE Std. 1149.1
  - Supports hot-socketing operation
  - Programmable ground pins
- Advanced architecture features
  - Programmable interconnect array (PIA) continuous routing structure for fast, predictable performance
  - Configurable expander product-term distribution, allowing up to 32 product terms per macrocell
  - Programmable macrocell registers with individual clear, preset, clock, and clock enable controls
  - Two global clock signals with optional inversion
  - Programmable power-up states for macrocell registers
  - 6 to 10 pin- or logic-driven output enable signals
- Advanced package options
  - Pin counts ranging from 44 to 256 in a variety of thin quad flat pack (TQFP), plastic quad flat pack (PQFP), ball-grid array (BGA), space-saving FineLine BGA™, 0.8-mm Ultra FineLine BGA, and plastic J-lead chip carrier (PLCC) packages
  - Pin-compatibility with other MAX 7000B devices in the same package
- Advanced software support
  - Software design support and automatic place-and-route provided by Altera's MAX+PLUS® II development system for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations

Table 3. MAX 7000B Maximum User I/O Pins *Note (1)*

Device	44-Pin PLCC	44-Pin TQFP	48-Pin TQFP *(2)*	49-Pin 0.8-mm Ultra FineLine BGA *(3)*	100-Pin TQFP	100-Pin FineLine BGA *(4)*	144-Pin TQFP	169-Pin 0.8-mm Ultra FineLine BGA *(3)*	208-Pin PQFP	256-Pin BGA	256-Pin FineLine BGA *(4)*
EPM7032B	36	36	36	36							
EPM7064B	36	36	40	41	68	68					
EPM7128B				41	84	84	100	100			100
EPM7256B					84		120	141	164		164
EPM7512B							120	141	176	212	212

Notes:

(1) When the IEEE Std. 1149.1 (JTAG) interface is used for in-system programming or boundary-scan testing, four I/O pins become JTAG pins.

(2) Contact Altera for up-to-date information on available device package options.

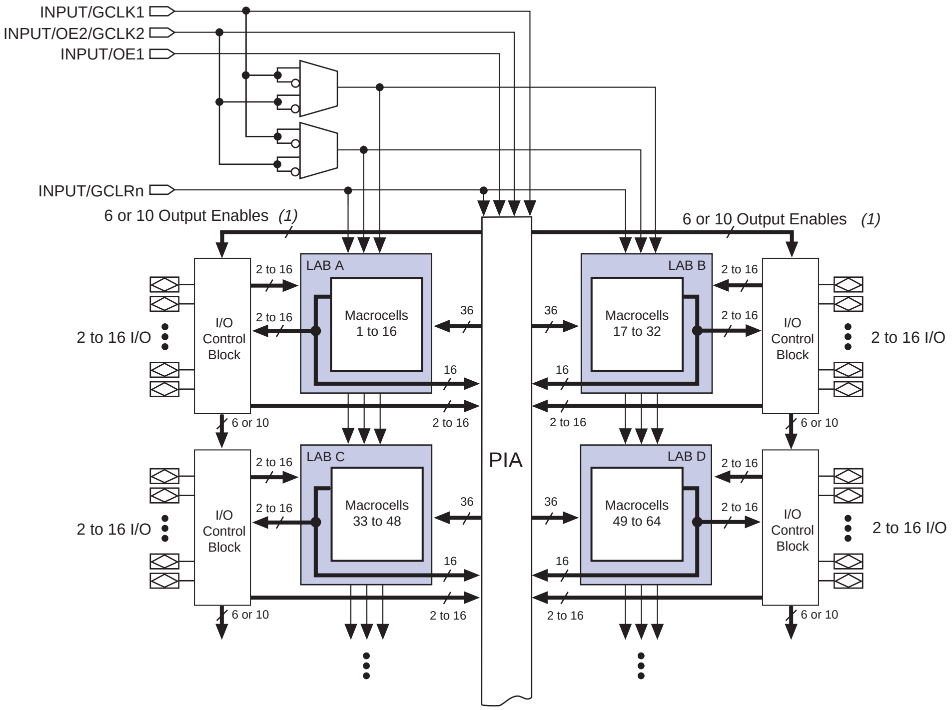
(3) All 0.8-mm Ultra FineLine BGA packages are footprint-compatible via the SameFrame^{TM} pin-out feature. Therefore, designers can design a board to support a variety of devices, providing a flexible migration path across densities and pin counts. Device migration is fully supported by Altera development tools. See "SameFrame Pin-Outs" on page 14 for more details.

(4) All FineLine BGA packages are footprint-compatible via the SameFrame pin-out feature. Therefore, designers can design a board to support a variety of devices, providing a flexible migration path across densities and pin counts. Device migration is fully supported by Altera development tools. See "SameFrame Pin-Outs" on page 14 for more details.

MAX 7000B devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000B architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

MAX 7000B devices contain 32 to 512 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-`AND`/fixed-`OR` array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

Figure 1. MAX 7000B Device Block Diagram



Note:

(1) EPM7032B, EPM7064B, EPM7128B, and EPM7256B devices have six output enables. EPM7512B devices have ten output enables.

Logic Array Blocks

The MAX 7000B device architecture is based on the linking of high-performance LABs. LABs consist of 16 macrocell arrays, as shown in Figure 1. Multiple LABs are linked together via the PIA, a global bus that is fed by all dedicated input pins, I/O pins, and macrocells.

Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the MAX+PLUS II software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- Global clock signal. This mode achieves the fastest clock-to-output performance.
- Global clock signal enabled by an active-high clock enable. A clock enable is generated by a product term. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- Array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

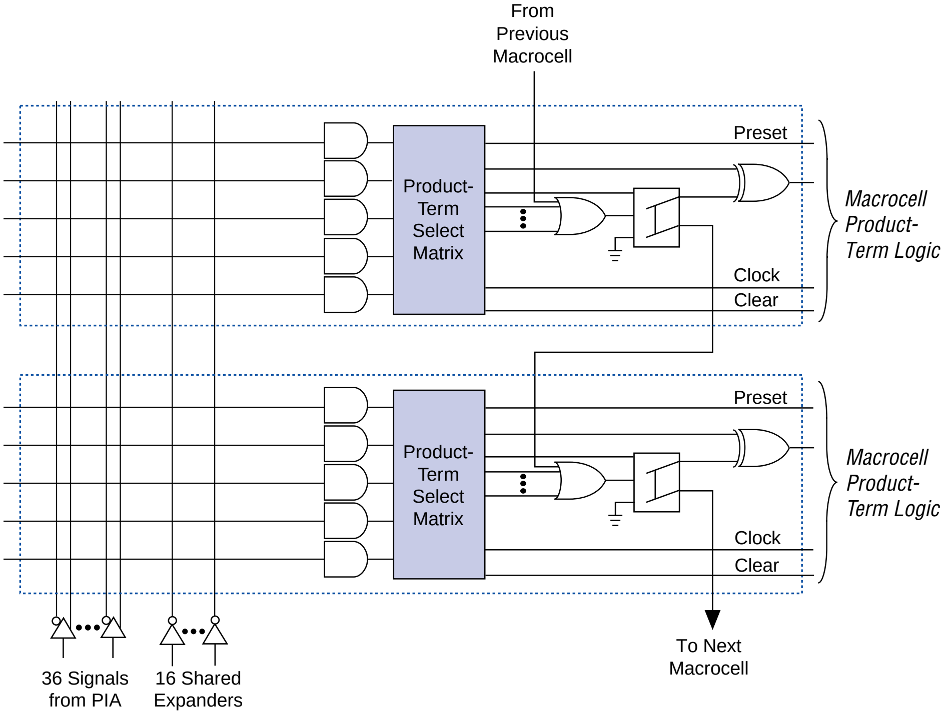
Two global clock signals are available in MAX 7000B devices. As shown in Figure 1, these global clock signals can be the true or the complement of either of the global clock pins, `GCLK1` or `GCLK2`.

Each register also supports asynchronous preset and clear functions. As shown in Figure 2, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear from the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (`GCLRn`). Upon power-up, each register in a MAX 7000B device may be set to either a high or low state. This power-up state is specified at design entry.

All MAX 7000B I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be clocked to an input D flipflop with an extremely fast input setup time. The input path from the I/O pin to the register has a programmable delay element that can be selected to either guarantee zero hold time or to get the fastest possible set-up time (as fast as 1.0 ns).

Figure 4. MAX 7000B Parallel Expanders

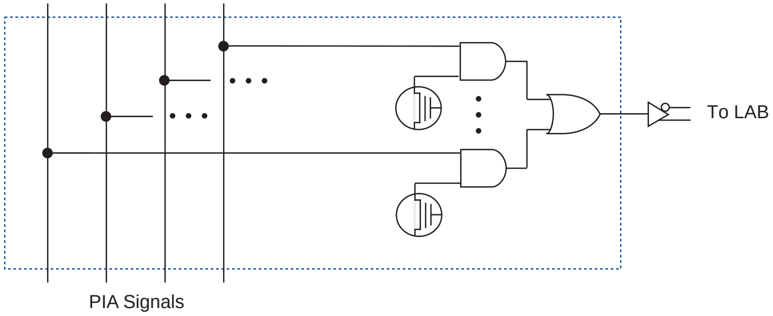
Unused product terms in a macrocell can be allocated to a neighboring macrocell.



Programmable Interconnect Array

Logic is routed between LABs on the PIA. This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000B dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 5 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a two-input AND gate, which selects a PIA signal to drive into the LAB.

Figure 5. MAX 7000B PIA Routing

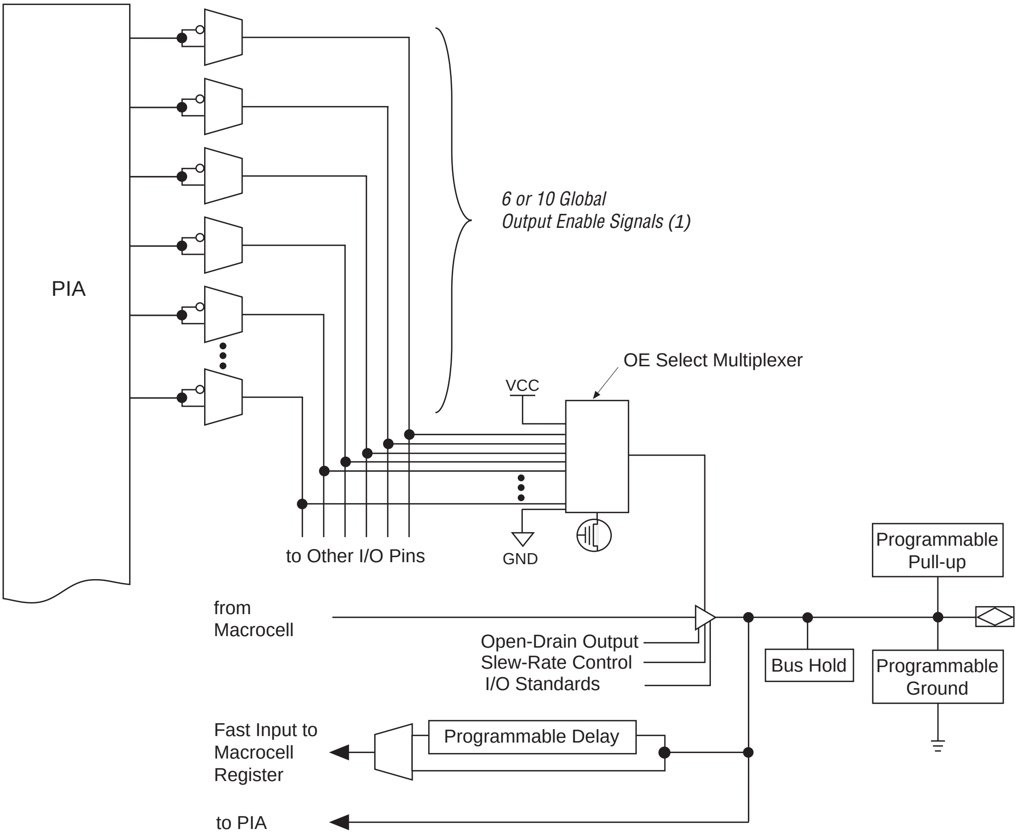


While the routing delays of channel-based routing schemes in masked or field-programmable gate arrays (FPGAs) are cumulative, variable, and path-dependent, the MAX 7000B PIA has a predictable delay. The PIA makes a design's timing performance easy to predict.

I/O Control Blocks

The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V_{CC}. Figure 6 shows the I/O control block for MAX 7000B devices. The I/O control block has six or ten global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

Figure 6. I/O Control Block of MAX 7000B Devices



Note:

(1) EPM7032B, EPM7064B, EPM7128B, and EPM7256B devices have six output enable signals. EPM7512B devices have ten output enable signals.

When the tri-state buffer control is connected to ground, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to V_{CC}, the output is enabled.

The MAX 7000B architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

In-System Programmability (ISP)

MAX 7000B devices can be programmed in-system via an industry-standard 4-pin IEEE Std. 1149.1 (JTAG) interface. ISP offers quick, efficient iterations during design development and debugging cycles. The MAX 7000B architecture internally generates the high programming voltages required to program EEPROM cells, allowing in-system programming with only a single 2.5-V power supply. During in-system programming, the I/O pins are tri-stated and weakly pulled-up to eliminate board conflicts. The pull-up value is nominally 50 k¾.

MAX 7000B devices have an enhanced ISP algorithm for faster programming. These devices also offer an ISP_Done bit that provides safe operation when in-system programming is interrupted. This ISP_Done bit, which is the last bit programmed, prevents all I/O pins from driving until the bit is programmed.

ISP simplifies the manufacturing flow by allowing devices to be mounted on a PCB with standard pick-and-place equipment before they are programmed. MAX 7000B devices can be programmed by downloading the information via in-circuit testers, embedded processors, the Altera MasterBlaster communications cable, and the ByteBlasterMV parallel port download cable. Programming the devices after they are placed on the board eliminates lead damage on high-pin-count packages (e.g., QFP packages) due to device handling. MAX 7000B devices can be reprogrammed after a system has already shipped to the field. For example, product upgrades can be performed in the field via software or modem.

In-system programming can be accomplished with either an adaptive or constant algorithm. An adaptive algorithm reads information from the unit and adapts subsequent programming steps to achieve the fastest possible programming time for that unit. A constant algorithm uses a pre-defined (non-adaptive) programming sequence that does not take advantage of adaptive algorithm programming time improvements. Some in-circuit testers cannot program using an adaptive algorithm. Therefore, a constant algorithm must be used. MAX 7000B devices can be programmed with either an adaptive or constant (non-adaptive) algorithm.

The Jam Standard Test and Programming Language (STAPL), JEDEC standard JESD-71, can be used to program MAX 7000B devices with in-circuit testers, PCs, or embedded processors.

For more information on using the Jam language, see *Application Note 88 (Using the Jam Language for ISP & ICR via an Embedded Processor)* and *Application Note 122 (Using STAPL for ISP & ICR via an Embedded Processor)*.

The ISP circuitry in MAX 7000B devices is compliant with the IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

Table 10. MAX 7000B MultiVolt I/O Support

V_{CCIO} (V)	Input Signal (V)				Output Signal (V)			
	1.8	2.5	3.3	5.0	1.8	2.5	3.3	5.0
1.8	✓	✓	✓		✓			
2.5	✓	✓	✓			✓		
3.3	✓	✓	✓				✓	✓

Open-Drain Output Option

MAX 7000B devices provide an optional open-drain (equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

Programmable Ground Pins

Each unused I/O pin on MAX 7000B devices may be used as an additional ground pin. This programmable ground feature does not require the use of the associated macrocell; therefore, the buried macrocell is still available for user logic.

Slew-Rate Control

The output buffer for each MAX 7000B I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. When the configuration cell is turned off, the slew rate is set for low-noise performance. Each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis. The slew rate control affects both the rising and falling edges of the output signal.

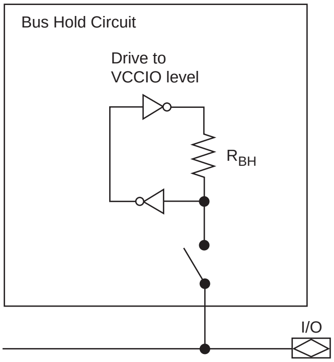
Advanced I/O Standard Support

The MAX 7000B I/O pins support the following I/O standards: LVTTL, LVCMOS, 1.8-V I/O, 2.5-V I/O, GTL+, SSTL-3 Class I and II, and SSTL-2 Class I and II.

Two inverters implement the bus-hold circuitry in a loop that weakly drives back to the I/O pin in user mode.

Figure 10 shows a block diagram of the bus-hold circuit.

Figure 10. Bus-Hold Circuit



PCI Compatibility

MAX 7000B devices are compatible with PCI applications as well as all 3.3-V electrical specifications in the ***PCI Local Bus Specification Revision 2.2*** except for the clamp diode. While having multiple clamp diodes on a signal trace may be redundant, designers can add an external clamp diode to meet the specification. Table 13 shows the MAX 7000B device speed grades that meet the PCI timing specifications.

Table 13. MAX 7000B Device Speed Grades that Meet PCI Timing Specifications

Device	Specification	
	33-MHz PCI	66-MHz PCI
EPM7032B	All speed grades	-3
EPM7064B	All speed grades	-3
EPM7128B	All speed grades	-4
EPM7256B	All speed grades	-5 *(1)*
EPM7512B	All speed grades	-5 *(1)*

Note:

(1) The EPM7256B and EPM7512B devices in a -5 speed grade meet all PCI timing specifications for 66-MHz operation except the Input Setup Time to CLK—Bused Signal parameter. However, these devices are within 1 ns of that parameter. EPM7256B and EPM7512B devices meet all other 66-MHz PCI timing specifications.

Power Sequencing & Hot-Socketing

Because MAX 7000B devices can be used in a mixed-voltage environment, they have been designed specifically to tolerate any possible power-up sequence. The V_{CCIO} and V_{CCINT} power planes can be powered in any order.

Signals can be driven into MAX 7000B devices before and during power-up (and power-down) without damaging the device. Additionally, MAX 7000B devices do not drive out during power-up. Once operating conditions are reached, MAX 7000B devices operate as specified by the user.

MAX 7000B device I/O pins will not source or sink more than 300 µA of DC current during power-up. All pins can be driven up to 4.1 V during hot-socketing.

Design Security

All MAX 7000B devices contain a programmable security bit that controls access to the data programmed into the device. When this bit is programmed, a design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security, because programmed data within EEPROM cells is invisible. The security bit that controls this function, as well as all other programmed data, is reset only when the device is reprogrammed.

Generic Testing

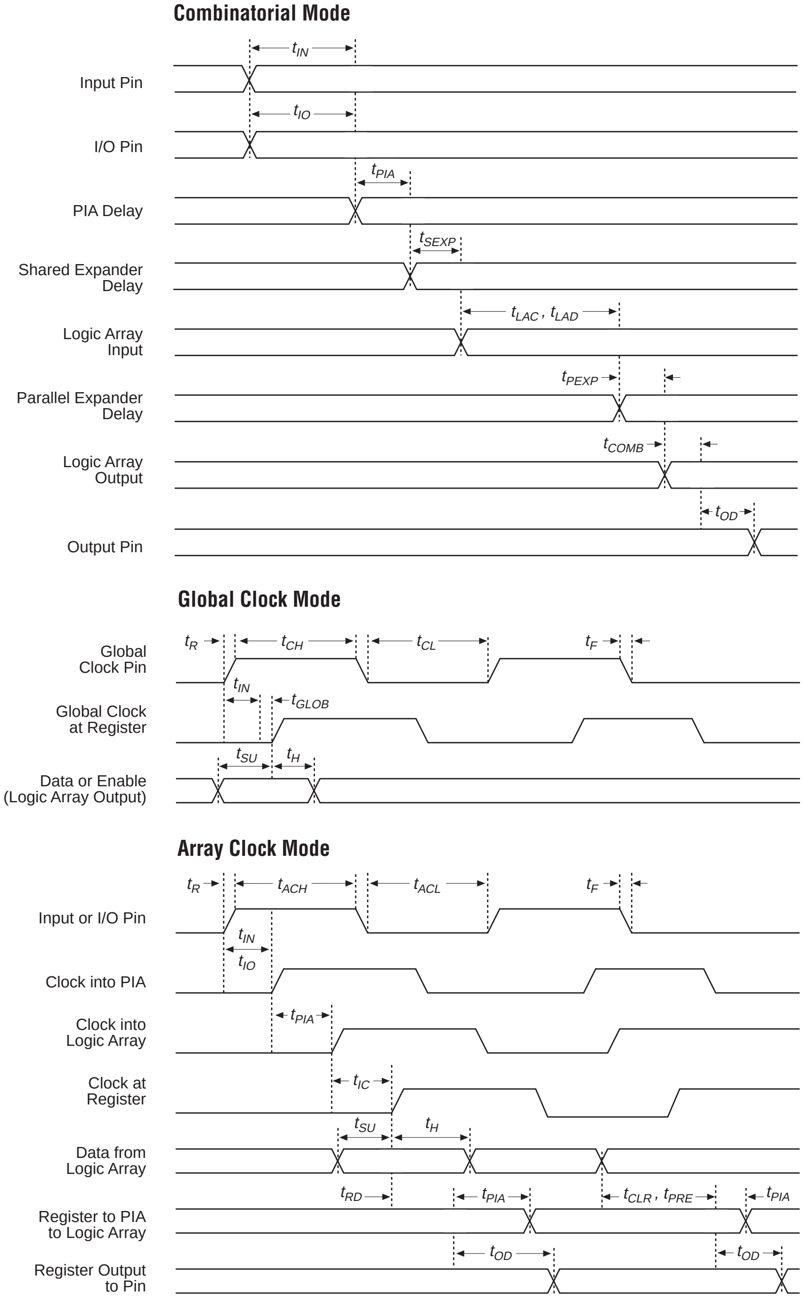
MAX 7000B devices are fully functionally tested. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in Figure 11. Test patterns can be used and then erased during early stages of the production flow.

Table 16. MAX 7000B Device DC Operating Conditions *Note (4)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{IH}	High-level input voltage for 3.3-V TTL/CMOS		2.0	3.9	V
	High-level input voltage for 2.5-V TTL/CMOS		1.7	3.9	V
	High-level input voltage for 1.8-V TTL/CMOS		0.65 × V_{CCIO}	3.9	V
V_{IL}	Low-level input voltage for 3.3-V TTL/CMOS and PCI compliance		–0.5	0.8	V
	Low-level input voltage for 2.5-V TTL/CMOS		–0.5	0.7	V
	Low-level input voltage for 1.8-V TTL/CMOS		–0.5	0.35 × V_{CCIO}	
V_{OH}	3.3-V high-level TTL output voltage	I_{OH} = –8 mA DC, V_{CCIO} = 3.00 V *(5)*	2.4		V
	3.3-V high-level CMOS output voltage	I_{OH} = –0.1 mA DC, V_{CCIO} = 3.00 V *(5)*	V_{CCIO} – 0.2		V
	2.5-V high-level output voltage	I_{OH} = –100 μA DC, V_{CCIO} = 2.30 V *(5)*	2.1		V
		I_{OH} = –1 mA DC, V_{CCIO} = 2.30 V *(5)*	2.0		V
		I_{OH} = –2 mA DC, V_{CCIO} = 2.30 V *(5)*	1.7		V
	1.8-V high-level output voltage	I_{OH} = –2 mA DC, V_{CCIO} =1.65 V *(5)*	1.2		V
V_{OL}	3.3-V low-level TTL output voltage	I_{OL} = 8 mA DC, V_{CCIO} = 3.00 V *(6)*		0.4	V
	3.3-V low-level CMOS output voltage	I_{OL} = 0.1 mA DC, V_{CCIO} = 3.00 V *(6)*		0.2	V
	2.5-V low-level output voltage	I_{OL} = 100 μA DC, V_{CCIO} = 2.30 V *(6)*		0.2	V
		I_{OL} = 1 mA DC, V_{CCIO} = 2.30 V *(6)*		0.4	V
		I_{OL} = 2 mA DC, V_{CCIO} = 2.30 V *(6)*		0.7	V
	1.8-V low-level output voltage	I_{OL} = 2 mA DC, V_{CCIO} = 1.7 V *(6)*		0.4	V
I_I	Input leakage current	V_I = –0.5 to 3.9 V *(7)*	–10	10	μA
I_{OZ}	Tri-state output off-state current	V_I = –0.5 to 3.9 V *(7)*	–10	10	μA
R_{ISP}	Value of I/O pin pull-up resistor during in-system programming or during power up	V_{CCIO} = 1.7 to 3.6 V *(8)*	20	74	k¾

Figure 14. MAX 7000B Switching Waveforms

t_R & t_F < 2 ns. Inputs are driven at 3.0 V for a logic high and 0 V for a logic low. All timing characteristics are measured at 1.5 V.



Tables 18 through 32 show MAX 7000B device timing parameters.

Table 18. EPM7032B External Timing Parameters *Notes (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-3.5		-5.0		-7.5		
			Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF *(2)*		3.5		5.0		7.5	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF *(2)*		3.5		5.0		7.5	ns
t_{SU}	Global clock setup time	*(2)*	2.1		3.0		4.5		ns
t_{H}	Global clock hold time	*(2)*	0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		1.0		1.0		1.5		ns
t_{FH}	Global clock hold time of fast input		1.0		1.0		1.0		ns
t_{FZHSU}	Global clock setup time of fast input with zero hold time		2.0		2.5		3.0		ns
t_{FZHH}	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF	1.0	2.4	1.0	3.4	1.0	5.0	ns
t_{CH}	Global clock high time		1.5		2.0		3.0		ns
t_{CL}	Global clock low time		1.5		2.0		3.0		ns
t_{ASU}	Array clock setup time	*(2)*	0.9		1.3		1.9		ns
t_{AH}	Array clock hold time	*(2)*	0.2		0.3		0.6		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF *(2)*	1.0	3.6	1.0	5.1	1.0	7.6	ns
t_{ACH}	Array clock high time		1.5		2.0		3.0		ns
t_{ACL}	Array clock low time		1.5		2.0		3.0		ns
t_{CPPW}	Minimum pulse width for clear and preset		1.5		2.0		3.0		ns
t_{CNT}	Minimum global clock period	*(2)*		3.3		4.7		7.0	ns
f_{CNT}	Maximum internal global clock frequency	*(2)*, *(3)*	303.0		212.8		142.9		MHz
t_{ACNT}	Minimum array clock period	*(2)*		3.3		4.7		7.0	ns
f_{ACNT}	Maximum internal array clock frequency	*(2)*, *(3)*	303.0		212.8		142.9		MHz

Table 19. EPM7032B Internal Timing Parameters *Notes (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-3.5		-5.0		-7.5		
			Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.3		0.5		0.7	ns
t_{IO}	I/O input pad and buffer delay			0.3		0.5		0.7	ns
t_{FIN}	Fast input delay			0.9		1.3		2.0	ns
t_{FIND}	Programmable delay adder for fast input			1.0		1.5		1.5	ns
t_{SEXP}	Shared expander delay			1.5		2.1		3.2	ns
t_{PEXP}	Parallel expander delay			0.4		0.6		0.9	ns
t_{LAD}	Logic array delay			1.4		2.0		3.1	ns
t_{LAC}	Logic control array delay			1.2		1.7		2.6	ns
t_{IOE}	Internal output enable delay			0.1		0.2		0.3	ns
t_{OD1}	Output buffer and pad delay slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		0.9		1.2		1.8	ns
t_{OD3}	Output buffer and pad delay slow slew rate = on V_{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		5.9		6.2		6.8	ns
t_{ZX1}	Output buffer enable delay slow slew rate = off V_{CCIO} = 3.3 V	C1 = 35 pF		1.6		2.2		3.4	ns
t_{ZX3}	Output buffer enable delay slow slew rate = on V_{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		6.6		7.2		8.4	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		1.6		2.2		3.4	ns
t_{SU}	Register setup time		0.7		1.1		1.6		ns
t_{H}	Register hold time		0.4		0.5		0.9		ns
t_{FSU}	Register setup time of fast input		0.8		0.8		1.1		ns
t_{FH}	Register hold time of fast input		1.2		1.2		1.4		ns
t_{RD}	Register delay			0.5		0.6		0.9	ns
t_{COMB}	Combinatorial delay			0.2		0.3		0.5	ns
t_{IC}	Array clock delay			1.2		1.8		2.8	ns
t_{EN}	Register enable time			1.2		1.7		2.6	ns
t_{GLOB}	Global control delay			0.7		1.1		1.6	ns
t_{PRE}	Register preset time			1.0		1.3		1.9	ns
t_{CLR}	Register clear time			1.0		1.3		1.9	ns
t_{PIA}	PIA delay	*(2)*		0.7		1.0		1.4	ns
t_{LPA}	Low-power adder	*(4)*		1.5		2.1		3.2	ns

Table 20. EPM7032B Selectable I/O Standard Timing Adder Delays *Notes (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-3.5		-5.0		-7.5		
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to (PIA)		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.3		0.4		0.6	ns
	Input to global clock and clear		0.3		0.4		0.6	ns
	Input to fast input register		0.2		0.3		0.4	ns
	All outputs		0.2		0.3		0.4	ns
1.8 V TTL/CMOS	Input to PIA		0.5		0.8		1.1	ns
	Input to global clock and clear		0.5		0.8		1.1	ns
	Input to fast input register		0.4		0.5		0.8	ns
	All outputs		1.2		1.8		2.6	ns
SSTL-2 Class I	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.8		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.3		1.9		2.8	ns
	Input to global clock and clear		1.2		1.8		2.6	ns
	Input to fast input register		0.9		1.3		1.9	ns
	All outputs		–0.1		–0.1		–0.2	ns
SSTL-3 Class I	Input to PIA		1.2		1.8		2.6	ns
	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.2		1.8		2.6	ns
	Input to global clock and clear		0.9		1.3		1.9	ns
	Input to fast input register		0.8		1.1		1.7	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.6		2.3		3.4	ns
	Input to global clock and clear		1.6		2.3		3.4	ns
	Input to fast input register		1.5		2.1		3.2	ns
	All outputs		0.0		0.0		0.0	ns

Table 29. EPM7256B Selectable I/O Standard Timing Adder Delays (Part 2 of 2) *Note (1)*

I/O Standard	Parameter	Speed Grade						Unit
		-5		-7		-10		
		Min	Max	Min	Max	Min	Max	
PCI	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns

Notes to tables:

(1) These values are specified under the Recommended Operating Conditions in Table 15 on page 29. See Figure 14 for more information on switching waveforms.

(2) These values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.

(3) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.

(4) The t_{LPA} parameter must be added to the t_{LAD}, t_{LAC}, t_{IC}, t_{ACL}, t_{CPPW}, t_{EN}, and t_{SEXP} parameters for macrocells running in low-power mode.

Table 30. EPM7512B External Timing Parameters *Note (1)*

Symbol	Parameter	Conditions	Speed Grade						Unit
			-5		-7		-10		
			Min	Max	Min	Max	Min	Max	
t_{PD1}	Input to non-registered output	C1 = 35 pF *(2)*		5.5		7.5		10.0	ns
t_{PD2}	I/O input to non-registered output	C1 = 35 pF *(2)*		5.5		7.5		10.0	ns
t_{SU}	Global clock setup time	*(2)*	3.6		4.9		6.5		ns
t_{H}	Global clock hold time	*(2)*	0.0		0.0		0.0		ns
t_{FSU}	Global clock setup time of fast input		1.0		1.5		1.5		ns
t_{FH}	Global clock hold time of fast input		1.0		1.0		1.0		ns
t_{FZHSU}	Global clock setup time of fast input with zero hold time		2.5		3.0		3.0		ns
t_{FZHH}	Global clock hold time of fast input with zero hold time		0.0		0.0		0.0		ns
t_{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.7	1.0	5.0	1.0	6.7	ns
t_{CH}	Global clock high time		3.0		3.0		4.0		ns
t_{CL}	Global clock low time		3.0		3.0		4.0		ns
t_{ASU}	Array clock setup time	*(2)*	1.4		1.9		2.5		ns
t_{AH}	Array clock hold time	*(2)*	0.5		0.6		0.8		ns
t_{ACO1}	Array clock to output delay	C1 = 35 pF *(2)*	1.0	5.9	1.0	8.0	1.0	10.7	ns
t_{ACH}	Array clock high time		3.0		3.0		4.0		ns
t_{ACL}	Array clock low time		3.0		3.0		4.0		ns
t_{CPPW}	Minimum pulse width for clear and preset		3.0		3.0		4.0		ns
t_{CNT}	Minimum global clock period	*(2)*		6.1		8.4		11.1	ns
f_{CNT}	Maximum internal global clock frequency	*(2)*, *(3)*	163.9		119.0		90.1		MHz
t_{ACNT}	Minimum array clock period	*(2)*		6.1		8.4		11.1	ns
f_{ACNT}	Maximum internal array clock frequency	*(2)*, *(3)*	163.9		119.0		90.1		MHz

Table 32. EPM7512B Selectable I/O Standard Timing Adder Delays (Part 1 of 2) Note (1)

I/O Standard	Parameter	Speed Grade						Unit
		-5		-7		-10		
		Min	Max	Min	Max	Min	Max	
3.3 V TTL/CMOS	Input to PIA		0.0		0.0		0.0	ns
	Input to global clock and clear		0.0		0.0		0.0	ns
	Input to fast input register		0.0		0.0		0.0	ns
	All outputs		0.0		0.0		0.0	ns
2.5 V TTL/CMOS	Input to PIA		0.4		0.5		0.7	ns
	Input to global clock and clear		0.3		0.4		0.5	ns
	Input to fast input register		0.2		0.3		0.3	ns
	All outputs		0.2		0.3		0.3	ns
1.8 V TTL/CMOS	Input to PIA		0.7		1.0		1.3	ns
	Input to global clock and clear		0.6		0.8		1.0	ns
	Input to fast input register		0.5		0.6		0.8	ns
	All outputs		1.3		1.8		2.3	ns
SSTL-2 Class I	Input to PIA		1.5		2.0		2.7	ns
	Input to global clock and clear		1.4		1.9		2.5	ns
	Input to fast input register		1.1		1.5		2.0	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-2 Class II	Input to PIA		1.5		2.0		2.7	ns
	Input to global clock and clear		1.4		1.9		2.5	ns
	Input to fast input register		1.1		1.5		2.0	ns
	All outputs		–0.1		–0.1		–0.2	ns
SSTL-3 Class I	Input to PIA		1.4		1.9		2.5	ns
	Input to global clock and clear		1.2		1.6		2.2	ns
	Input to fast input register		1.0		1.4		1.8	ns
	All outputs		0.0		0.0		0.0	ns
SSTL-3 Class II	Input to PIA		1.4		1.9		2.5	ns
	Input to global clock and clear		1.2		1.6		2.2	ns
	Input to fast input register		1.0		1.4		1.8	ns
	All outputs		0.0		0.0		0.0	ns
GTL+	Input to PIA		1.8		2.5		3.3	ns
	Input to global clock and clear		1.9		2.6		3.5	ns
	Input to fast input register		1.8		2.5		3.3	ns
	All outputs		0.0		0.0		0.0	ns

Figure 28. 256-Pin BGA Package Pin-Out Diagram

Package outline not drawn to scale.